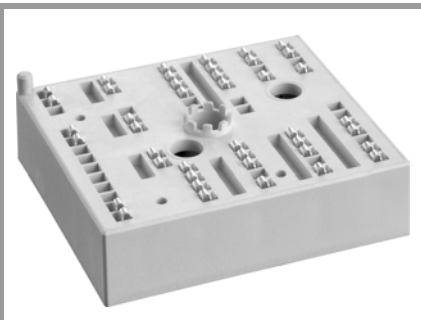


# SKiiP 23AC12T4V1



MiniSKiiP® 2

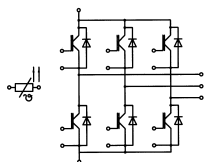
## SKiiP 23AC12T4V1

### Features

- Trench 4 IGBT's
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised file no. E63532

### Remarks

- $V_{CEsat}$ ,  $V_F$  = chip level value
- Case temp. limited to  $T_C = 125^\circ\text{C}$  max. (for baseplateless modules  $T_C = T_S$ )
- product rel. results valid for  $T_j \leq 150$  (recomm. Top =  $-40 \dots +150^\circ\text{C}$ )

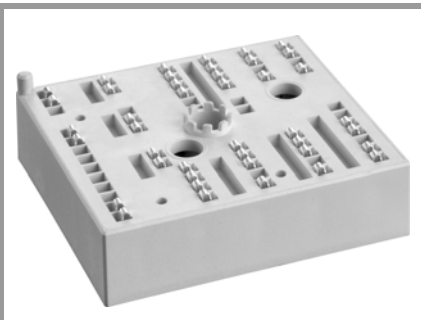


AC

Absolute Maximum Ratings				
Symbol	Conditions		Values	Unit
<b>Inverter - IGBT</b>				
$V_{CES}$	$T_j = 25^\circ\text{C}$		1200	V
$I_C$	$T_j = 175^\circ\text{C}$	$T_s = 25^\circ\text{C}$	41	A
		$T_s = 70^\circ\text{C}$	34	A
$I_{Cnom}$			25	A
$I_{CRM}$	$I_{CRM} = 3 \times I_{Cnom}$		75	A
$V_{GES}$			-20 ... 20	V
$t_{psc}$	$V_{CC} = 800\text{ V}$	$T_j = 150^\circ\text{C}$	10	$\mu\text{s}$
	$V_{GE} \leq 15\text{ V}$			
	$V_{CES} \leq 1200\text{ V}$			
$T_j$			-40 ... 175	$^\circ\text{C}$
<b>Inverse - Diode</b>				
$I_F$	$T_j = 175^\circ\text{C}$	$T_s = 25^\circ\text{C}$	32	A
		$T_s = 70^\circ\text{C}$	26	A
$I_{Fnom}$			25	A
$I_{FRM}$	$I_{FRM} = 3 \times I_{Fnom}$		75	A
$I_{FSM}$	10 ms, sin $180^\circ$ , $T_j = 150^\circ\text{C}$		100	A
$T_j$			-40 ... 175	$^\circ\text{C}$
<b>Module</b>				
$I_{t(RMS)}$	$T_{terminal} = 80^\circ\text{C}$ , 20A per spring		100	A
$T_{stg}$			-40 ... 125	$^\circ\text{C}$
$V_{isol}$	AC sinus 50Hz, t = 1 min		2500	V

Characteristics							
Symbol	Conditions		min.	typ.	max.	Unit	
<b>Inverter - IGBT</b>							
$V_{CE(sat)}$	$I_C = 25\text{ A}$	$T_j = 25^\circ\text{C}$	1.85	2.10		V	
		$T_j = 150^\circ\text{C}$	2.25	2.45		V	
$V_{CE0}$			$T_j = 25^\circ\text{C}$	0.8	0.9	V	
			$T_j = 150^\circ\text{C}$	0.7	0.8	V	
$r_{CE}$	$V_{GE} = 15\text{ V}$	$T_j = 25^\circ\text{C}$	42	48		$\text{m}\Omega$	
		$T_j = 150^\circ\text{C}$	62	66		$\text{m}\Omega$	
$V_{GE(th)}$	$V_{GE} = V_{CE}$ , $I_C = 1\text{ mA}$		5	5.8	6.5	V	
$I_{CES}$	$V_{GE} = 0\text{ V}$	$T_j = 25^\circ\text{C}$			0.1	0.3	mA
					$V_{CE} = 1200\text{ V}$		
$C_{ies}$	$V_{CE} = 25\text{ V}$	$V_{GE} = 0\text{ V}$	$f = 1\text{ MHz}$		1.43	nF	
$C_{oes}$			$f = 1\text{ MHz}$		0.12	nF	
$C_{res}$			$f = 1\text{ MHz}$		0.09	nF	
$Q_G$	$-8\text{ V} \dots +15\text{ V}$				142	nC	
$R_{Gint}$	$T_j = 25^\circ\text{C}$				0.00	$\Omega$	
$t_{d(on)}$	$V_{CC} = 600\text{ V}$	$T_j = 150^\circ\text{C}$			44	ns	
$t_r$	$I_C = 25\text{ A}$	$T_j = 150^\circ\text{C}$			46	ns	
		$T_j = 150^\circ\text{C}$			3.7	mJ	
$E_{on}$	$R_{Gon} = 39\ \Omega$	$T_j = 150^\circ\text{C}$			3.7	mJ	
	$R_{Goff} = 39\ \Omega$	$T_j = 150^\circ\text{C}$			330	ns	
$t_{d(off)}$	$di/dt_{on} = 465\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$			330	ns	
$t_f$	$di/dt_{off} = 350\text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$			62	ns	
$E_{off}$	$V_{GE} = +15/-15\text{ V}$	$T_j = 150^\circ\text{C}$			2.4	mJ	
$R_{th(j-s)}$	per IGBT				1	K/W	

# SKiiP 23AC12T4V1



MiniSKiiP® 2

## SKiiP 23AC12T4V1

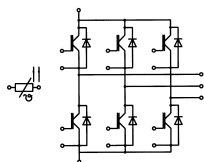
### Features

- Trench 4 IGBT's
- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised file no. E63532

### Remarks

- $V_{CEsat}$ ,  $V_F$  = chip level value
- Case temp. limited to  $T_C = 125^\circ\text{C}$  max. (for baseplateless modules  $T_C = T_S$ )
- product rel. results valid for  $T_j \leq 150$  (recomm. Top =  $-40 \dots +150^\circ\text{C}$ )

Characteristics						
Symbol	Conditions		min.	typ.	max.	Unit
<b>Inverse - Diode</b>						
$V_F = V_{EC}$	$I_F = 25 \text{ A}$ $V_{GE} = 0 \text{ V}$ chiplevel	$T_j = 25^\circ\text{C}$		2.4	2.7	V
		$T_j = 150^\circ\text{C}$		2.5	2.8	V
$V_{F0}$		$T_j = 25^\circ\text{C}$		1.3	1.5	V
		$T_j = 150^\circ\text{C}$		0.9	1.1	V
$r_F$		$T_j = 25^\circ\text{C}$		44	50	m $\Omega$
		$T_j = 150^\circ\text{C}$		62	68	m $\Omega$
$I_{RRM}$	$I_F = 25 \text{ A}$	$T_j = 150^\circ\text{C}$		19		A
$Q_{rr}$	$di/dt_{off} = 640 \text{ A}/\mu\text{s}$	$T_j = 150^\circ\text{C}$		4		$\mu\text{C}$
$E_{rr}$	$V_{GE} = -15 \text{ V}$ $V_{CC} = 600 \text{ V}$	$T_j = 150^\circ\text{C}$		1.64		mJ
$R_{th(j-s)}$	per Diode			1.52		K/W
<b>Module</b>						
$M_s$	to heat sink		2		2.5	Nm
w				65		g
<b>Temperatur Sensor</b>						
$R_{100}$	$T_C = 100^\circ\text{C}$ ( $R_{25} = 1000\Omega$ )			$1670 \pm 3\%$		$\Omega$
$R(T)$	$R(T) = 1000\Omega [1 + A(T - 25^\circ\text{C}) + B(T - 25^\circ\text{C})^2]$ ], $A = 7.635 \cdot 10^{-3} \text{ }^\circ\text{C}^{-1}$ , $B = 1.731 \cdot 10^{-5} \text{ }^\circ\text{C}^{-2}$					



AC

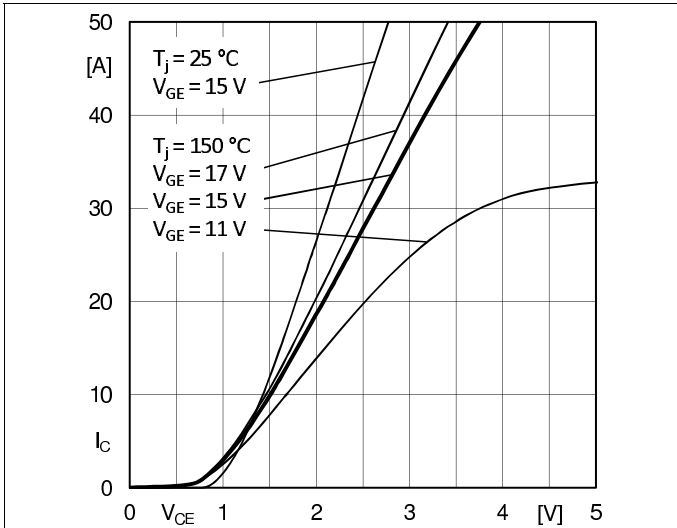


Fig. 1: Typ. output characteristic, inclusive  $R_{CC'+EE'}$

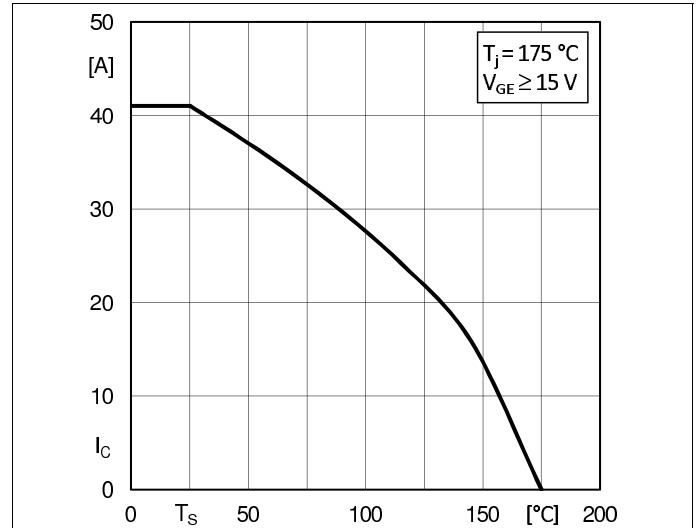


Fig. 2: Rated current vs. temperature  $I_C = f(T_S)$

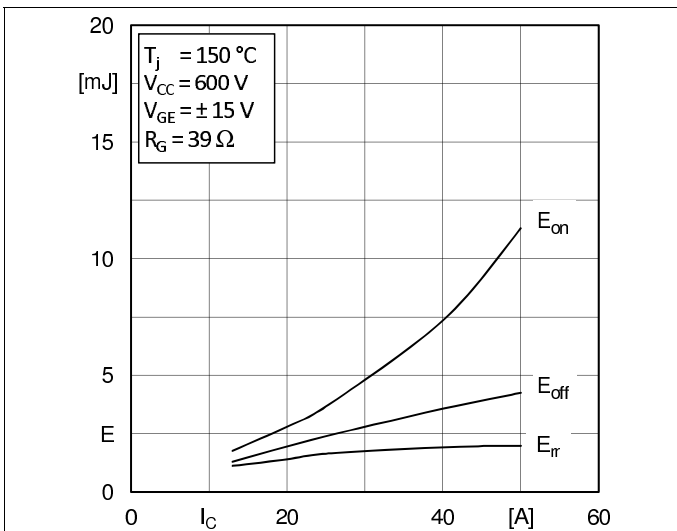


Fig. 3: Typ. turn-on /-off energy =  $f(I_C)$

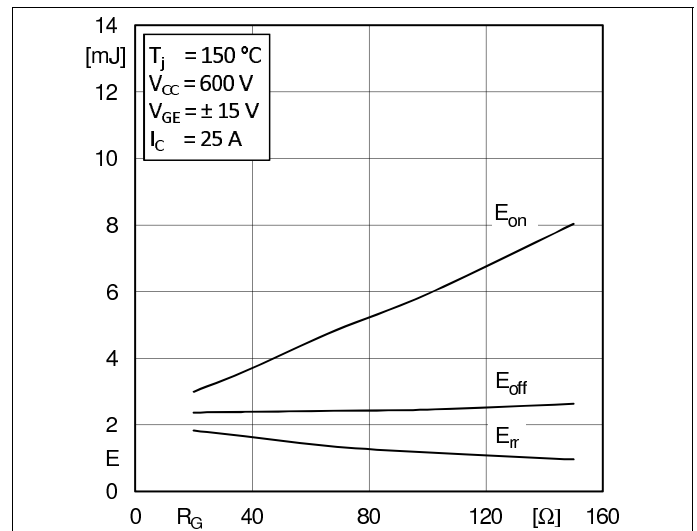


Fig. 4: Typ. turn-on /-off energy =  $f(R_G)$

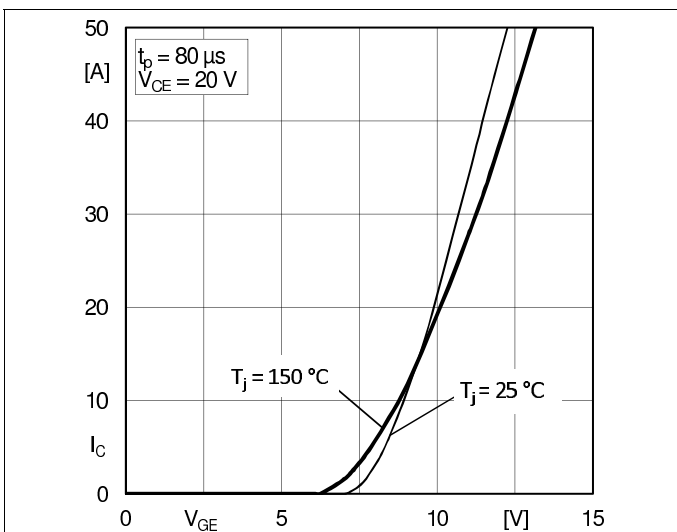


Fig. 5: Typ. transfer characteristic

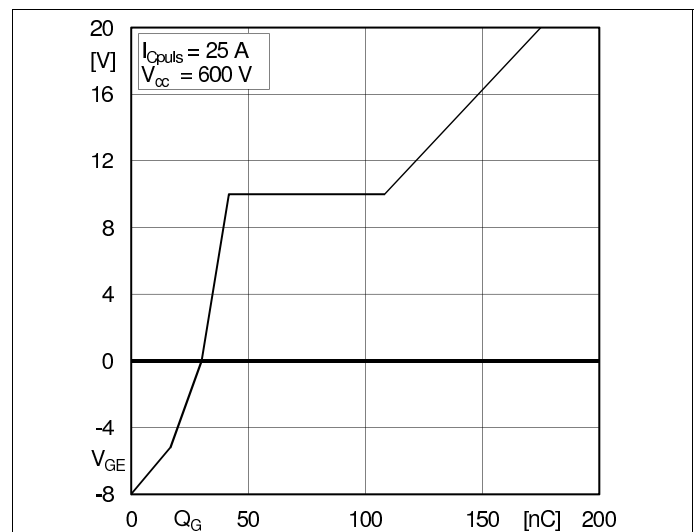


Fig. 6: Typ. gate charge characteristic

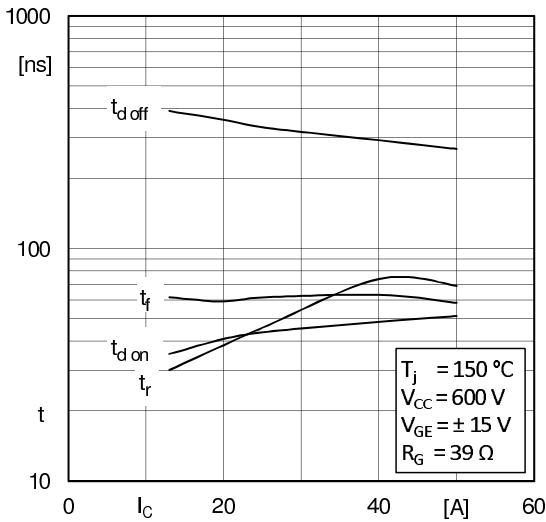


Fig. 7: Typ. switching times vs.  $I_C$

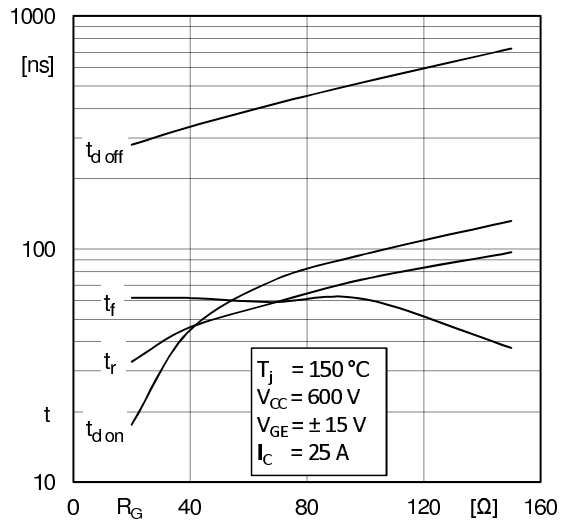


Fig. 8: Typ. switching times vs. gate resistor  $R_G$

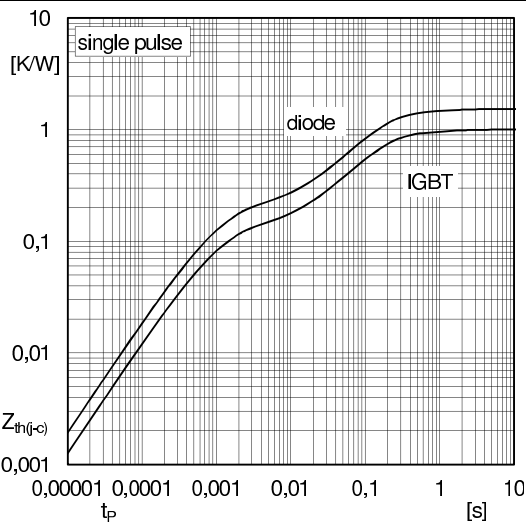


Fig. 9: Transient thermal impedance of IGBT and Diode

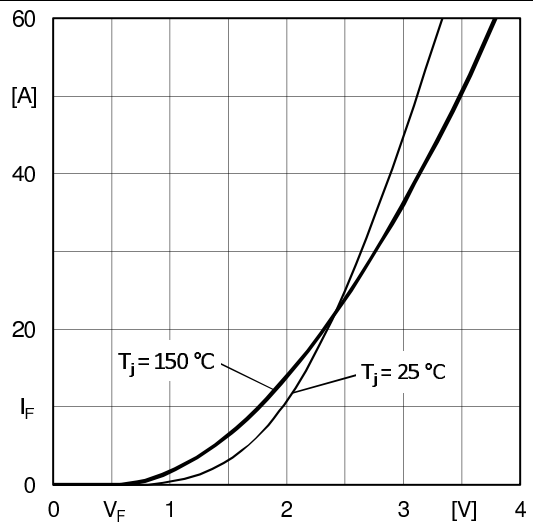


Fig. 10: CAL diode forward characteristic

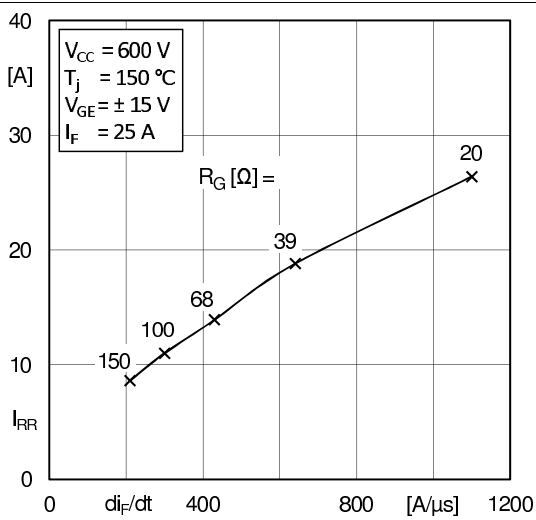


Fig. 11: Typ. CAL diode peak reverse recovery current

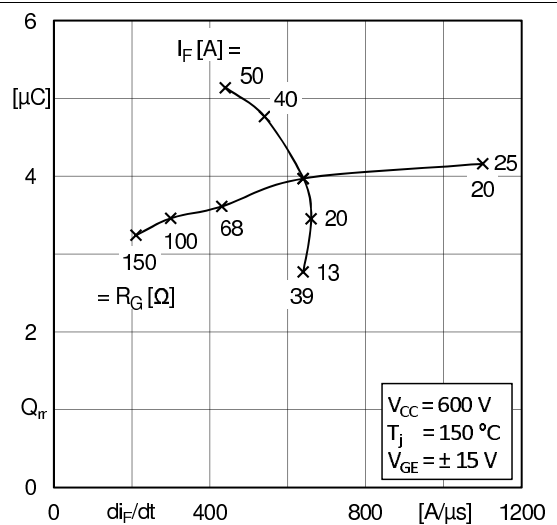
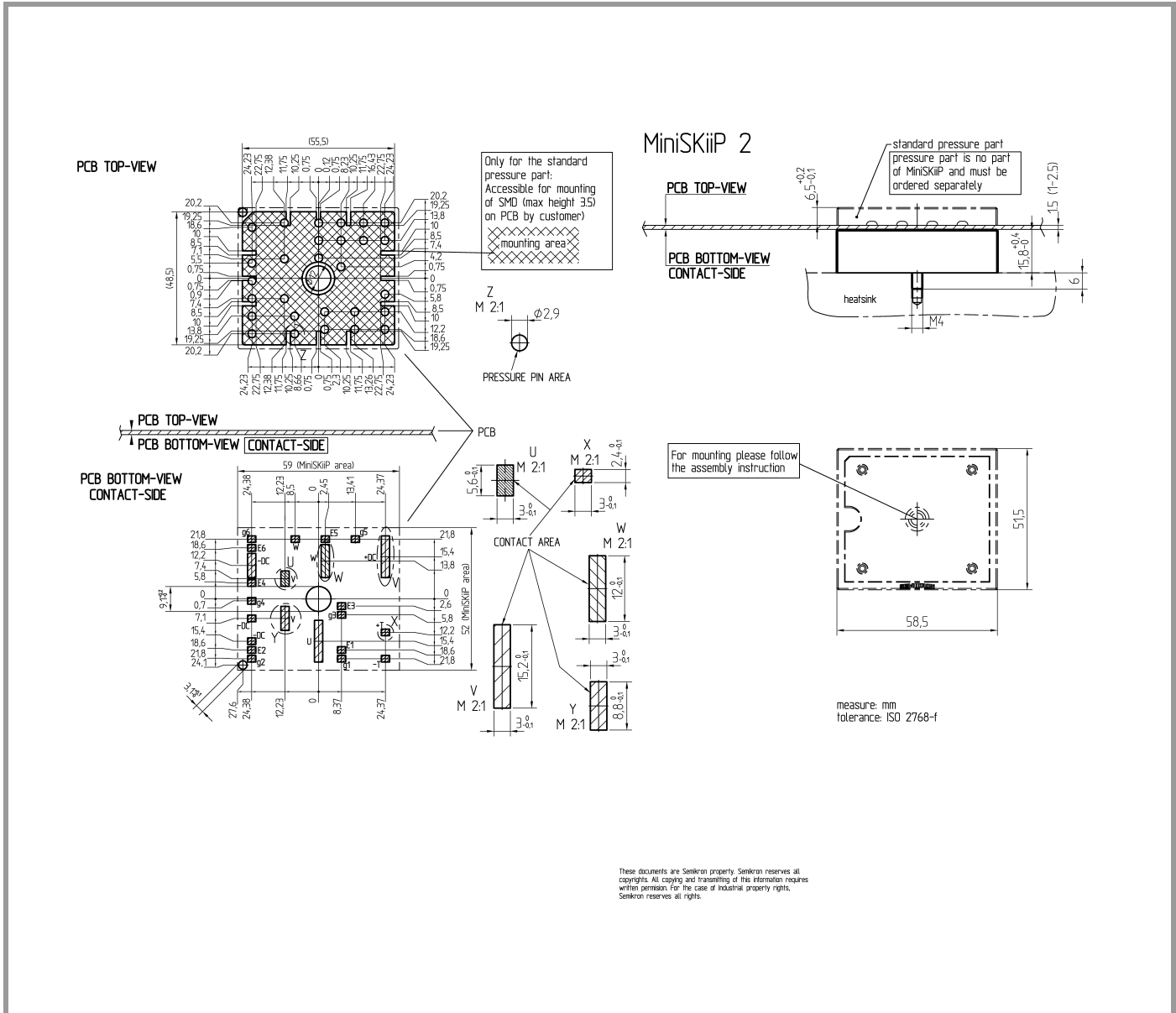
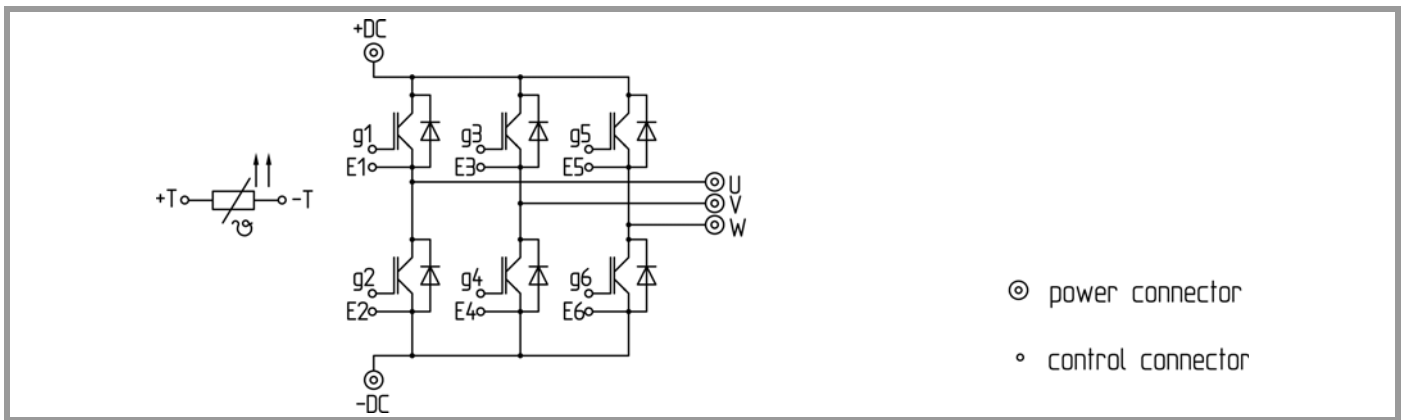


Fig. 12: Typ. CAL diode recovery charge

# SKiiP 23AC12T4V1



pinout, dimensions



pinout

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our staff.